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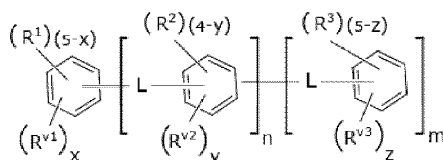
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(54) Title: POLYVINYL SUBSTITUTED DI- AND TRI-PHENYL COMPOUNDS FOR USE IN FORMING SPIN-ON LAYERS



(I)

(57) Abstract: The present invention relates to a new chemical com-
pound represented by chemical formula (I). The compound can be a
kind of advanced material or high performance material, and can be
used for Inkjet Adaptive Planarization composition. It can be used in
the nanotechnology process to make semiconductor device/display
device application, for example liquid crystal, quantum dot or OLED
display fabricated on a substrate, and controlled by semiconductors.



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